



SPECIFICATION

(Reference sheet)

- Supplier : Samsung electro-mechanics - Samsung P/N : CL10C120JB8NNND

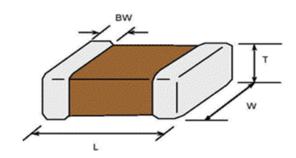
• Product : Multi-layer Ceramic Capacitor • Description : CAP, 12pF, 50V, ± 5%, C0G, 0603

A. Samsung Part Number

<u>CL</u> <u>10</u> <u>C</u> <u>120</u> <u>J</u> <u>B</u> <u>8</u> <u>N</u> <u>N</u> <u>N</u> <u>D</u> ① ② ③ ④ ⑤ ⑥ ⑦ ⑧ ⑨ ⑩ ⑪

| ① Series | Samsung Multi-layer Cera | amic Capacitor | |
|---------------|--------------------------|-------------------|--------------------------|
| ② Size | 0603 (inch code) | L: 1.60 ± 0.10 mm | W: 0.80 ± 0.10 mm |
| | | | |
| 3 Dielectric | C0G | 8 Inner electrode | Ni |
| ④ Capacitance | 12 pF | Termination | Cu |
| ⑤ Capacitance | ± 5 % | Plating | Sn 100% (Pb Free) |
| tolerance | | Product | Normal |
| Rated Voltage | 50 V | Special | Reserved for future use |
| ① Thickness | 0.80 ± 0.10 mm | Packaging | Cardboard Type, 13" reel |

B. Structure and dimension



| Samsung P/N | Dimension(mm) | | | |
|-----------------|---------------|-------------|-------------|-------------|
| (Lead Free) | L | W | Т | BW |
| CL10C120JB8NNND | 1.60 ± 0.10 | 0.80 ± 0.10 | 0.80 ± 0.10 | 0.30 ± 0.20 |

C. Samsung Reliability Test and Judgement condition

| CapacitanceWithin specified tolerance1Mt±10%0.5~5VrmsQ640 minRated Voltage60~120 sec.Insulation10,000Mohm or 500Mohm×μFRated Voltage60~120 sec.ResistanceWhichever is smallerMicroscope (*10)AppearanceNo abnormal exterior appearanceMicroscope (*10)WithstandingNo dielectric breakdown or voltage300% of the rated voltageTemperatureC0GCharacteristics(From -55 ℃ to 125 ℃, Capacitance change should be within ±30PPM/ ℃)Adhesive Strength of TerminationNo peeling shall be occur on the terminal electrode500g×F, for 10±1 sec.Bending StrengthCapacitance change : within ±5% or ±0.5 pF whichever is largerBending to the limit (1mm) within 1.0mm/sec.SolderabilityMore than 75% of terminal surfaceSnAg3.0Cu0.5 solder |
|--|
| Insulation 10,000Mohm or 500Mohm×µF Rated Voltage 60~120 sec. Resistance Whichever is smaller Microscope (*10) Appearance No abnormal exterior appearance Microscope (*10) Withstanding No dielectric breakdown or 300% of the rated voltage Voltage mechanical breakdown Temperature C0G Characteristics (From -55 °C to 125 °C, Capacitance change should be within ±30PPM/°C) Adhesive Strength No peeling shall be occur on the 500g×F, for 10±1 sec. of Termination terminal electrode Bending to the limit (1mm) Bending Strength Capacitance change : with 1.0mm/sec. Solderability More than 75% of terminal surface SnAg3.0Cu0.5 solder |
| Resistance Appearance No abnormal exterior appearance Microscope (´10) Withstanding No dielectric breakdown or Woltage Temperature COG Characteristics (From -55°C to 125°C, Capacitance change should be within ±30PPM/°C) Adhesive Strength of Termination Bending Strength Capacitance change: Whichever is smaller Microscope (´10) 300% of the rated voltage Microscope (´10) Solderability Microscope (´10) Solderabiler Appearance Microscope (´10) Solderabiler Bending Strength Cog Characteristics (From -55°C to 125°C, Capacitance change should be within ±30PPM/°C) No peeling shall be occur on the 500g×F, for 10±1 sec. Solderability Bending to the limit (1mm) within ±5% or ±0.5pF whichever is larger With 1.0mm/sec. Solderability More than 75% of terminal surface SnAg3.0Cu0.5 solder |
| Appearance No abnormal exterior appearance Microscope (′10) Withstanding No dielectric breakdown or mechanical breakdown 300% of the rated voltage Temperature C0G Characteristics (From -55 ℃ to 125 ℃, Capacitance change should be within ±30PPM/℃) Adhesive Strength of Termination No peeling shall be occur on the terminal electrode 500g×F, for 10±1 sec. Bending Strength Capacitance change : with 1.0mm/sec. Bending to the limit (1mm) with 1.0mm/sec. Solderability More than 75% of terminal surface SnAg3.0Cu0.5 solder |
| Withstanding No dielectric breakdown or mechanical breakdown 300% of the rated voltage Temperature C0G Characteristics (From -55℃ to 125℃, Capacitance change should be within ±30PPM/℃) Adhesive Strength of Termination No peeling shall be occur on the terminal electrode 500g×F, for 10±1 sec. Bending Strength Capacitance change : with 1.0mm/sec. Bending to the limit (1mm) within ±5% or ±0.5pF whichever is larger Solderability More than 75% of terminal surface SnAg3.0Cu0.5 solder |
| Voltage mechanical breakdown Temperature C0G Characteristics (From -55 °C to 125 °C, Capacitance change should be within ±30PPM/°C) Adhesive Strength of Termination No peeling shall be occur on the terminal electrode 500g×F, for 10±1 sec. Bending Strength within ±5% or ±0.5 pF whichever is larger Bending to the limit (1mm) with 1.0mm/sec. Solderability More than 75% of terminal surface SnAg3.0Cu0.5 solder |
| Temperature C0G Characteristics (From -55 °C to 125 °C, Capacitance change should be within ±30PPM/°C) Adhesive Strength of Termination No peeling shall be occur on the terminal electrode Bending Strength Capacitance change : within ±5% or ±0.5 pF whichever is larger Bending to the limit (1mm) within ±5% or ±0.5 pF whichever is larger Solderability More than 75% of terminal surface SnAg3.0Cu0.5 solder |
| Characteristics (From -55 ℃ to 125 ℃, Capacitance change should be within ±30PPM/ ℃) Adhesive Strength of Termination No peeling shall be occur on the terminal electrode 500g×F, for 10±1 sec. Bending Strength within ±5% or ±0.5 pF whichever is larger Bending to the limit (1mm) with 1.0mm/sec. Solderability More than 75% of terminal surface SnAg3.0Cu0.5 solder |
| Adhesive Strength of Termination Bending Strength Within ±5% or ±0.5pF whichever is larger Solderability No peeling shall be occur on the terminal electrode 500g×F, for 10±1 sec. Bending to the limit (1mm) with 1.0mm/sec. Solderability More than 75% of terminal surface SnAg3.0Cu0.5 solder |
| of Termination terminal electrode Bending Strength Capacitance change : within ±5% or ±0.5 pF whichever is larger Bending to the limit (1mm) with 1.0mm/sec. Solderability More than 75% of terminal surface SnAg3.0Cu0.5 solder |
| Bending Strength Capacitance change : within ±5% or ±0.5 pF whichever is larger Bending to the limit (1mm) with 1.0mm/sec. Solderability More than 75% of terminal surface SnAg3.0Cu0.5 solder |
| within ±5% or ±0.5pF whichever is larger with 1.0mm/sec. Solderability More than 75% of terminal surface SnAg3.0Cu0.5 solder |
| Solderability More than 75% of terminal surface SnAg3.0Cu0.5 solder |
| |
| |
| is to be soldered newly 245±5 °C, 3±0.3sec. |
| (preheating : 80~120 ℃ for 10~30sec.) |
| |
| Resistance to Capacitance change : Solder pot : 270±5°C, 10±1sec. |
| Soldering heat within ±2.5% or ±0.25pF whichever is larger |
| Tan δ, IR : initial spec. |
| Vibration Test Capacitance change : Amplitude : 1.5mm |
| within ±2.5% or ±0.25pF whichever is larger From 10Hz to 55Hz (return : 1min.) |
| Tan δ, IR: initial spec. 2hours ´3 direction (x, y, z) |
| Moisture Capacitance change : With rated voltage |
| Resistance within ±7.5% or ±0.75pF whichever is larger 40±2°C, 90~95%RH, 500+12/-0hrs |
| Q: 140 min |
| IR: 500Mohm or 25Mohm × μ F |
| Whichever is smaller |
| High Temperature Capacitance change : With 200% of the rated voltage |
| Resistance within ±3% or ±0.3pF whichever is larger Max. operating temperature |
| Q: 305 min 1000+48/-0hrs |
| IR: 1,000Mohm or 50Mohm × μ F |
| Whichever is smaller |
| Temperature Capacitance change : 1 cycle condition |
| Cycling within $\pm 2.5\%$ or $\pm 0.25 pF$ whichever is larger Min. operating temperature \rightarrow 25 °C |
| Tan δ, IR : initial spec. \rightarrow Max. operating temperature \rightarrow 25 °C |
| |
| |
| 5 cycle test |

^{*} The reliability test condition can be replaced by the corresponding accelerated test condition.

D. Recommended Soldering method:

Reflow (Reflow Peak Temperature : 260+0/-5℃, 10sec. Max)



A Product specifications included in the specifications are effective as of March 1, 2013.

Please be advised that they are standard product specifications for reference only.

We may change, modify or discontinue the product specifications without notice at any time.

So, you need to approve the product specifications before placing an order.

Should you have any question regarding the product specifications,

please contact our sales personnel or application engineers.

- Disclaimer & Limitation of Use and Application -

The products listed in this Specification sheet are **NOT** designed and manufactured for any use and applications set forth below.

Please note that any misuse of the products deviating from products specifications or information provided in this Spec sheet may cause serious property damages or personal injury.

We will **NOT** be liable for any damages resulting from any misuse of the products, specifically including using the products for high reliability applications as listed below.

If you have any questions regarding this 'Limitation of Use and Application', you should first contact our sales personnel or application engineers.

- ① Aerospace/Aviation equipment
- ② Automotive or Transportation equipment (vehicles, trains, ships, etc)
- 3 Medical equipment
- Military equipment
- 5 Disaster prevention/crime prevention equipment
- Any other applications with the same as or similar complexity or reliability to the applications set forth above.